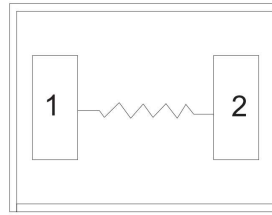


Features

- Large resistances
- Small size
- Can customize according to requirements

Function Diagram

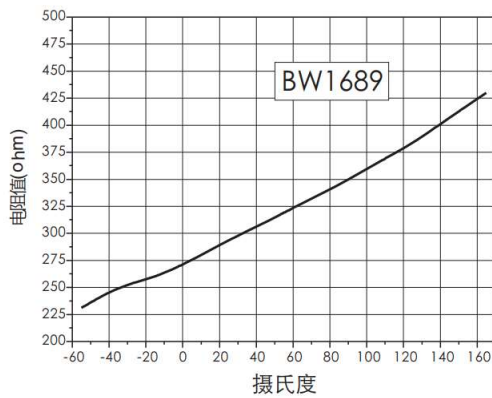


Electrical Specifications (Ta=+25°C)

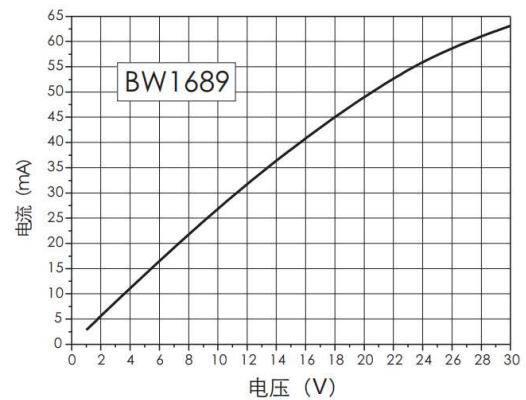
Part Number	Resistance			Unit
	Min.	Typ.	Max.	Ω
BW1689	270	300	330	Ω
BW1690	450	500	550	Ω
BW1691	540	600	660	Ω
BW1692	900	1000	1100	Ω
BW1693	1800	2000	2200	Ω
BW1694	3600	4000	4400	Ω
BW1695	5400	6000	6600	Ω

Test Curves (Die chip)

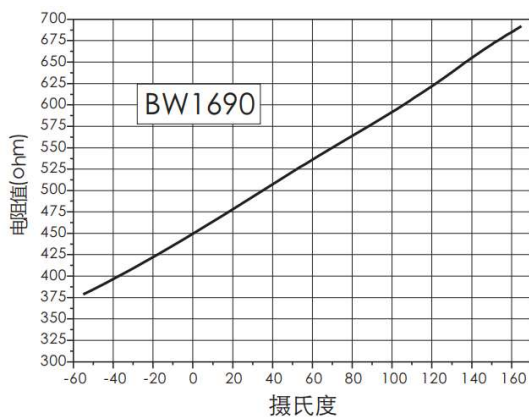
Resistance vs. Temperature



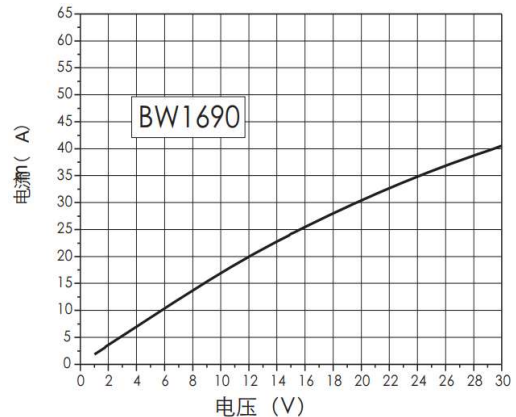
IV Curve (Ta=+25°C)



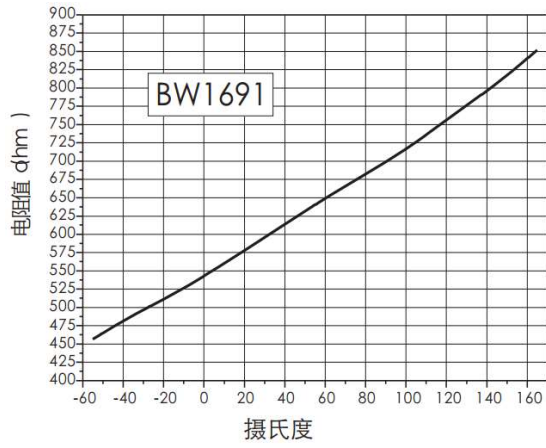
Resistance vs. Temperature



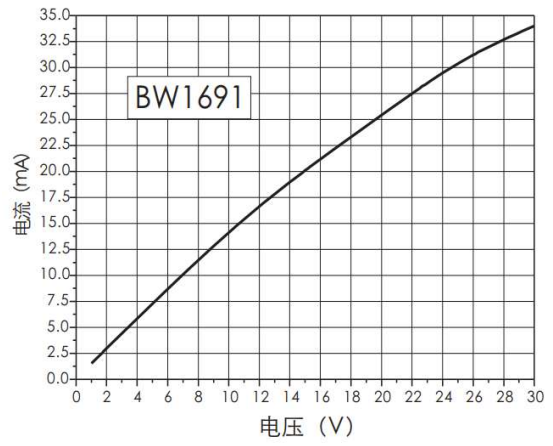
IV Curve (Ta=+25°C)



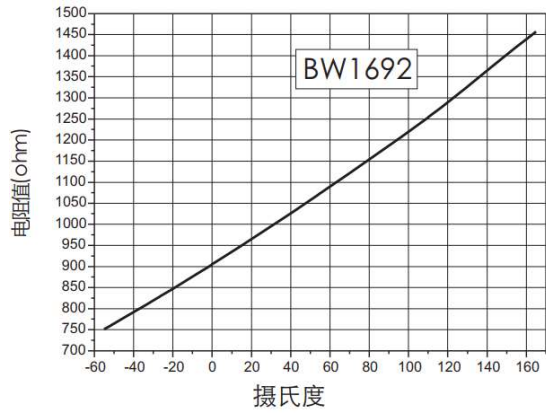
Resistance vs. Temperature



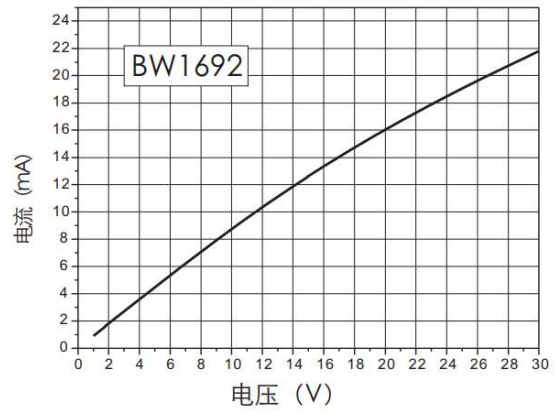
IV Curve (Ta=+25°C)



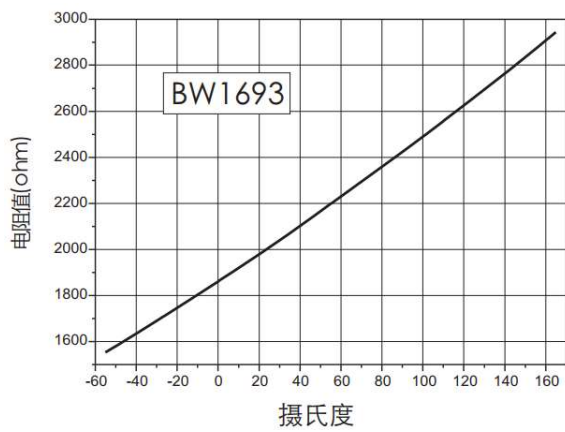
Resistance vs. Temperature



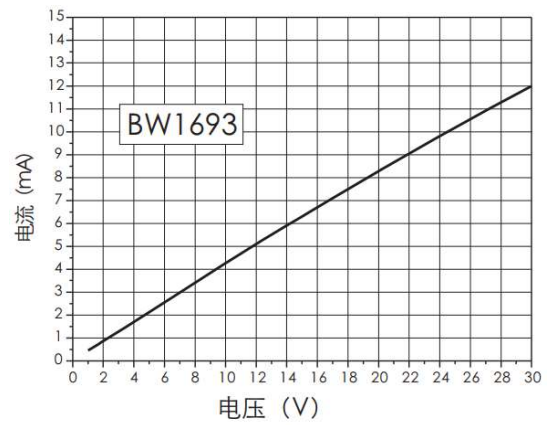
IV Curve (Ta=+25°C)



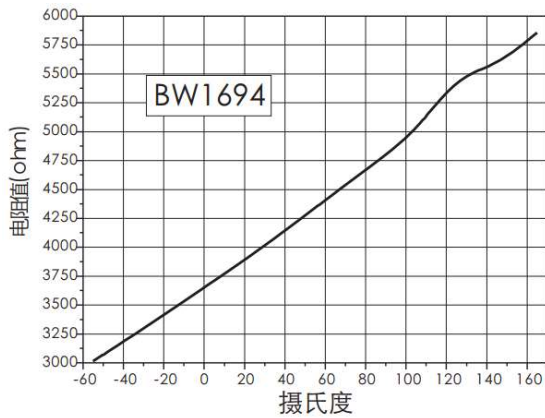
Resistance vs. Temperature



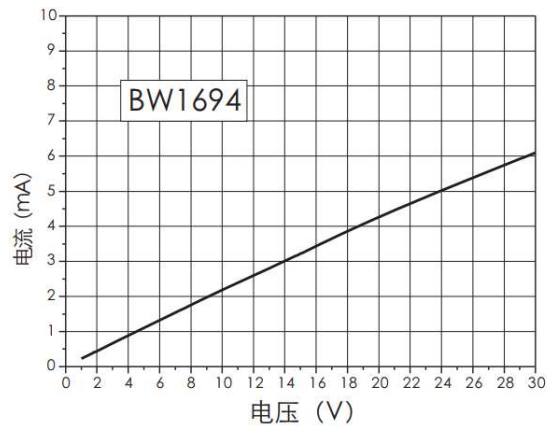
IV Curve (Ta=+25°C)



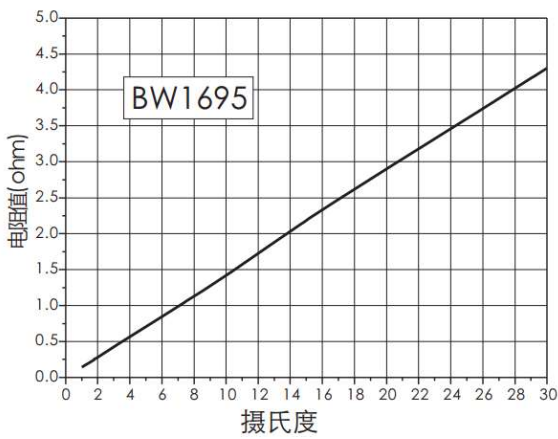
Resistance vs. Temperature



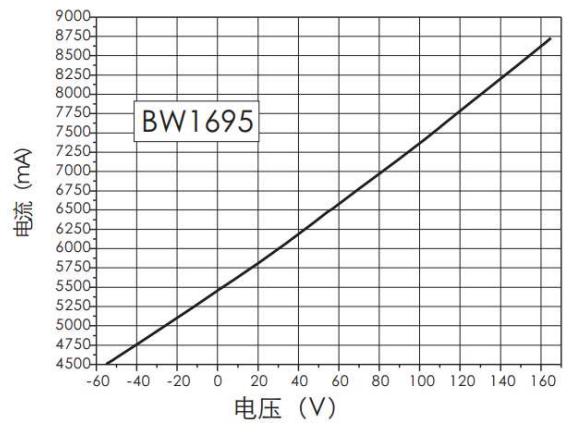
IV Curve (Ta=+25°C)



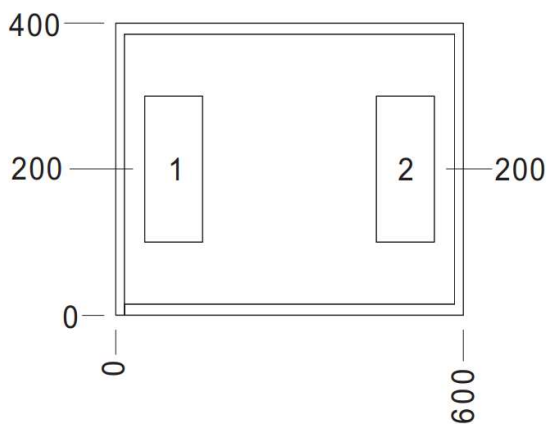
Resistance vs. Temperature



IV Curve (Ta=+25°C)



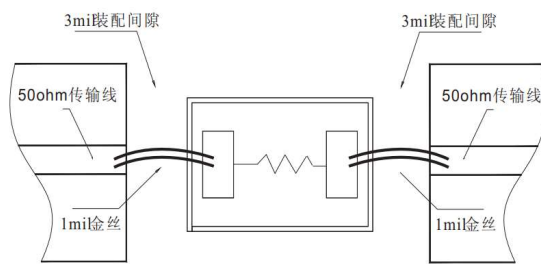
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, Pad size: 100*100(um)
5. Don't bonding on thru holes
6. Tolerance: ±50um

Application



Absolute Rating

Max. Handling current	2mA
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Bonding Pads Definition

Number	Symbol	Description
1、2	In, Out	Any two ports can be used as input or output
	GND	Bottom must be grounded